



ADVANCED PROCESS/PRODUCT CHANGE NOTIFICATION

APCN MPA/06/2033
Notification Date 10/03/2006

Advanced Information

Cu on Ag spot D2PAK/I2PAK/P2PAK in Shenzhen plant

MPA - MPA

Table 1. Change Identification

Product Identification (Product Family/Commercial Product)	Volt Reg & Power MOSFET in D2PAK/I2PAK/P2PAK
Type of change	Package assembly material change
Reason for change	To improve Quality and Reliability
Description of the change	Currently D2PAK/I2PAK/P2PAK packages are assembled for V.Reg's by using Au bonding wires on Ag spot lead frame, while for Power MOSFET by using Aluminium bonding wires on spot Ni lead frame. Forthcoming the same products are qualifying copper bonding wires on Ag spot lead frame.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	
Change Product Identification	See letter "S" as additional info field
Manufacturing Location(s)	1]St Shenzhen -China

Table 2. Change Implementation Schedule

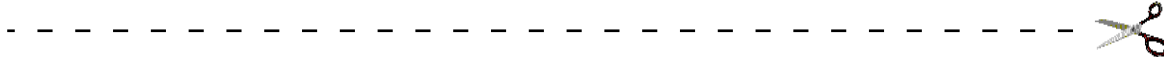
Forecasted implementation date for change	27-Dec-2006
Forecasted availability date of samples for customer	20-Sep-2006
Forecasted date for STMicroelectronics change Qualification Plan results availability	05-Dec-2006
Estimated date of changed product first shipment	27-Dec-2006

Table 3. Change Responsibility

	Name	Signature	Date
Division Product Manager	Marco Pesce/Ian Wilson		Sep.20 ,06
Division Q.A. Manager	G.Vitali/G.Falcone		Sep.20 ,06
Division Marketing Manager	M.Sanbiagio/M.Giudice		Sep.20 ,06

Table 4. List of Attachments

Customer Part numbers list	
Qualification Plan results	



Customer Acknowledgement of Receipt		APCN MPA/06/2033
Please sign and return to STMicroelectronics Sales Office		Notification Date 10/03/2006
<input type="checkbox"/> Qualification Plan Denied <input type="checkbox"/> Qualification Plan Approved <input type="checkbox"/> Change Denied <input type="checkbox"/> Change Approved	Name:	
	Title:	
	Company:	
	Date:	
	Signature:	
Remark		

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